

TDS:EMIC

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自主封測 品質把控 售後保障

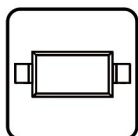
WEB | WWW.TDSEMIC.COM



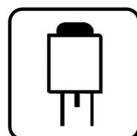
電源管理



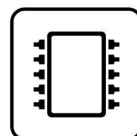
顯示驅動



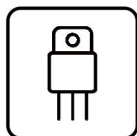
二三極管



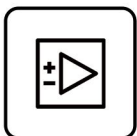
LDO穩壓器



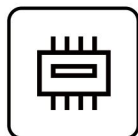
觸摸芯片



MOS管



運算放大器



存儲芯片



MCU



串口通信

1N4007WS 7A-TD

產品規格說明書

FEATURES

- Low profile space
- Ideal for automated placement
- Glass passivated chip junctions
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals

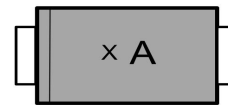


VOLTAGE RANGE

50 to 1000 Volts

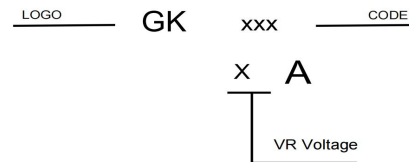
CURRENT

1.0 Ampere



MECHANICAL DATA

- **Case:** SOD-323 molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per JESD22-B102
- **Polarity:** Laser band denotes cathode end



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Items	Symbol	1N4001WS 1A	1N4002WS 2A	1N4003WS 3A	1N4004WS 4A	1N4005WS 5A	1N4006WS 6A	1N4007WS 7A	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	1							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	15							A
Thermal resistance from junction to lead ⁽¹⁾	$R_{\theta JL}$	35							°C/W
Operating junction range	T_J	-55 to +150							°C
storage temperature range	T_{STG}	-55 to +150							°C

Note 1: Mounted on PCB with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Items	Test conditions	Symbol	Min	Type	Max	UNIT
Instantaneous forward voltage	$I_F = 0.5\text{A}$	V_F	-	0.92	-	V
	$I_F = 1\text{A}^{(2)}$			0.98	1.1	
Reverse current	$V_R = V_{DC}$	I_R	-	-	5	μA
					50	

Note 2: Pulse test: 300 μs pulse width, 1% duty cycle.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

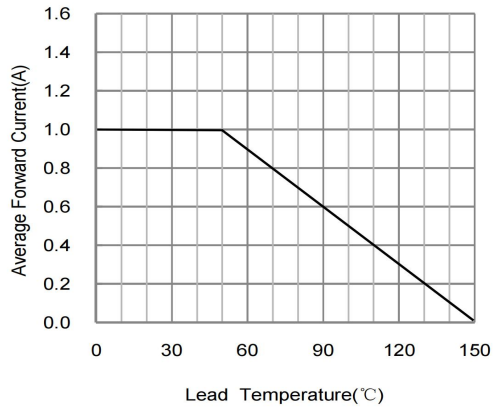


FIG.2-TYPICAL FORWARD CHARACTERISTICS

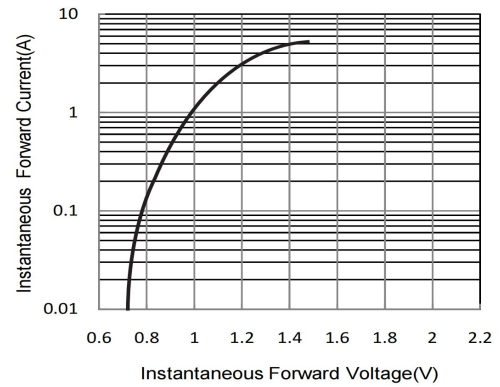


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

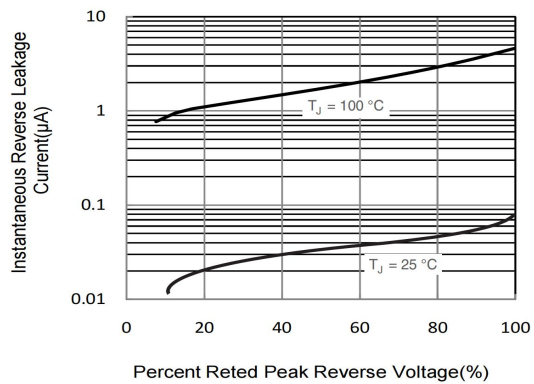
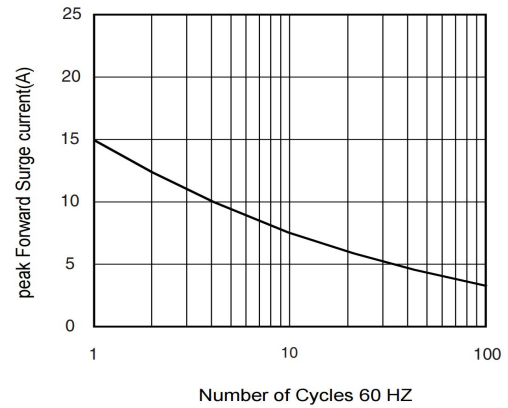
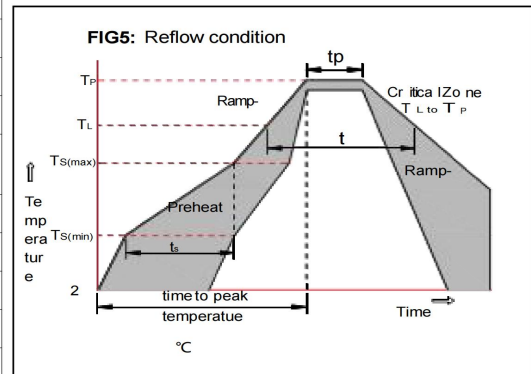


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



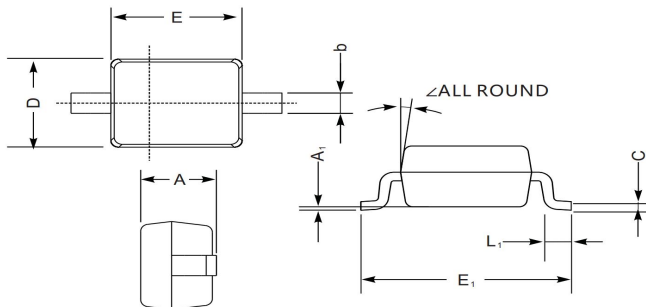
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



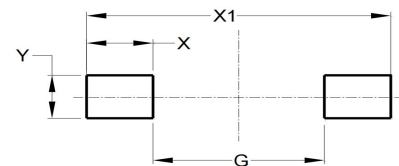
Package Dimensions & Suggested Pad Layout

SOD323



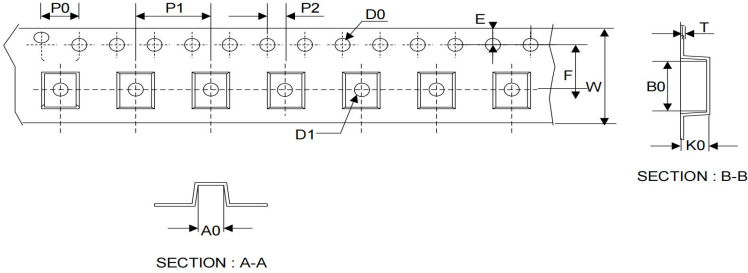
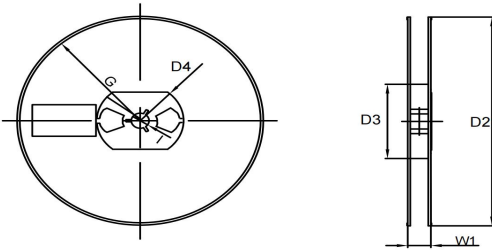
SOD-323 mechanical data

UNIT		A	C	D	E	E ₁	b	L ₁	A ₁	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	



Dimensions	Value (in mm)
G	1.40
X	1.20
X1	3.80
Y	1.00

ape & rell specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
7" Reel		P1	4.00±0.20
		P2	2.00±0.20
		D0	1.55±0.20
		D1	1.00±0.20
		E	1.55±0.25
		F	3.60±0.20
		W	8.00±0.20
		A0	2.00±0.20
		B0	3.25±0.20
		K0	1.35±0.20
		T	0.23±0.10
		D2	177.0±5.0
		D3	55Min.
		D4	R24.6±2.0
		G	R82.0±2.0
		I	13.0±2.0
		W1	10.20±3.0
		Quantity: 3000PCS	